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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chopra et al.

Serial No.: 10/620,002

Filed: July 14, 2003

For: SLURRY FOR USE WITH FIXED-
ABRASIVE POLISHING PADS IN
POLISHING SEMICONDUCTOR DEVICE
CONDUCTIVE STRUCTURES THAT
INCLUDE COPPER AND TUNGSTEN

Confirmation No.: 7481

Examiner: L. Umez-Eronini

Group Art Unit: 1765

Attorney Docket No.: 2269-4373.2US
(00-0036.02/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

August 24, 2006
Date

Signature

Erika Gandre

Name (Type/Print)

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of any cited foreign patents, publications, or pending unpublished U.S. applications are enclosed pursuant to 37 C.F.R. § 1.98(a)(2).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

Other Documents

GUTMANN, ET AL., Chemical-mechanical polishing of copper with oxide and polymer interlevel dielectrics, Thin Solid Films 270:596-600 (1995).

ZEIDLER, ET AL., The interaction between different barrier metals and the copper surface during the chemical-mechanical polishing, Microelectronic Engineering 37/38:237-249 (1997).

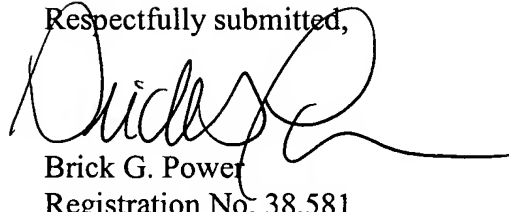
Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits.

I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement, and therefore no fee is due.

Serial No. 10/620,002

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Brick G. Power", written over the typed name.

Brick G. Power
Registration No. 38,581
Attorney for Applicants
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: August 24, 2006
BGP/djp:eg

Enclosures: Form PTO/SB/08
Cited Non-U.S. Patent Documents

Document in ProLaw



PTO/SB/08B(10-03)

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet

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of

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Complete if Known

Application Number	10/620,002
Filing Date	July 14, 2003
First Named Inventor	Chopra et al.
Group Art Unit	1765
Examiner Name	L. Umez-Eronini
Attorney Docket Number	2269-4373 211S (00-0036 02/1S)

NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		GUTMANN, ET AL., Chemical-mechanical polishing of copper with oxide and polymer interlevel dielectrics, Thin Solid Films 270:596-600 (1995).	
		ZEIDLER, ET AL., The interaction between different barrier metals and the copper surface during the chemical-mechanical polishing, Microelectronic Engineering 37/38:237-249 (1997).	

Examiner
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